CRA04S

Vishay



Thick Film Resistor Array



The CRA04S thick film resistor array is constructed on a high grade ceramic body with convex terminations. A small package enables the design of high density circuits. The single component reduces board space, component counts, and assembly costs.

FEATURES

- · Convex terminal array with square corners
- Wide ohmic ramge: 10R to 1M0
- 4 or 8 terminal package with isolated resistors
- · Lead (Pb)-free solder contacts on Ni barrier layer
- Pure tin plating provides compatibility with lead (Pb)-free and lead containing soldering processes
- Compatible with "Restriction of the use of Hazardous Substances" (RoHS) directive 2002/95/EC (issue 2004)

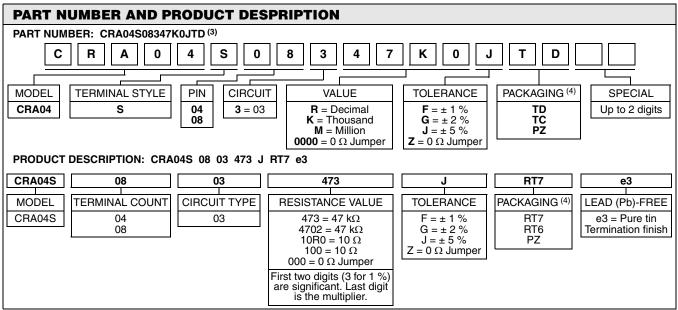
STANDARD ELECTRICAL SPECIFICATIONS									
MODEL	CIRCUIT	POWER RATING P70 °C W	LIMITING ELEMENT VOLTAGE MAX. V≅	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	RESISTANCE RANGE Ω	E-SERIES		
	03	0.063	50	± 100	± 1	10R - 1M0	24 + 96		
CRA04S			50	± 200	± 2; ± 5		24		
		Zero-Ohm-Resistor: $R_{\text{max.}} \le 50 \text{ m}\Omega$, $I_{\text{max.}} = 1 \text{ A}$							

TECHNICAL SPECIFICATIONS				
PARAMETER	UNIT	CRA04S		
Rated Dissipation at 70 °C (2)	W per element	0.063		
Limiting Element Voltage (1)	V≅	50		
Insulation Voltage (1 min)	V _{dc/ac peak}	100		
Category Temperature Range	°C	- 55 to + 155		
Insulation Resistance	Ω	> 10 ⁹		

Notes

⁽¹⁾ Rated voltage: $\sqrt{P \times R}$

(2) The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rate dissipation applies only if the permitted film temperature of 155 °C is not exceeded.



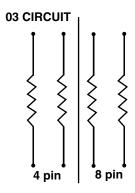
Notes

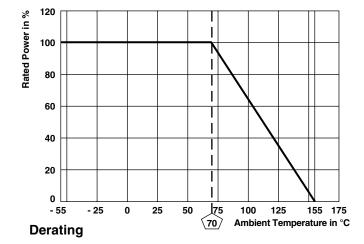
⁽³⁾ Preferred way for ordering products is by use of the PART NUMBER
⁽⁴⁾ Please refer to the table PACKAGING, see next page



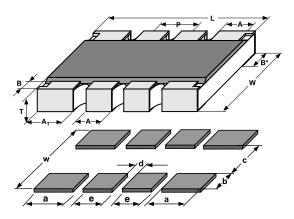
PACKAGING							
					PAC	KAGING CODE	
MODEL	TAPE WIDTH	DIAMETER	РІТСН	PIECES/REEL	PAPER TAPE		
					PART NUMBER	PRODUCT DESCRIPTION	
		180 mm/7"	2 mm	10 000	TD	RT7	
CRA04S	8 mm	330 mm/13"	2 mm	20 000	тс	RT6	
		330 mm/13"	2 mm	50 000	ΡZ	PZ	

CIRCUIT





DIMENSIONS



PIN	DIMENSIONS [in millimeters]								
NO#	L	Α	A 1	В	B*	P _{NOM}	Т	W	
4	1.0 ± 0.1	-	0.33	0.15	0.25	0.65	0.35	1.0	
8	2.0 ± 0.2	0.30	0.4	0.15	0.25	0.50	0.45	1.0	
TOL.	-	± 0.15	± 0.15	± 0.10	± 0.1	-	± 0.1	± 0.15	

SOLDER PAD DIMENSIONS [in millimeters]						
	С	w	d	а	b	е
WAVE	0.45	1.45	0.2	0.4	0.5	0.3

The dimensions shown are for a 8 pin part. For parts with different pin numbers use the same pitch and add or substract pads as required.



TEST PROCEDURES AND REQUIREMENTS						
EN 60115-1						
TEST	CONDITIONS OF TEST	REQUIREMENTS PERMISSIBLE CHANGE (<i>\(\Delta R/R\)</i>) ⁽¹⁾				
(clause)	CONDITIONS OF TEST	STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER			
	Stability for product types:	10.0 % 1.10	10 Ω to 1 M Ω			
	CRA04S	10 Ω to 1 M Ω				
Resistance (4.5)	-	± 1 %	± 2 %; ± 5 %			
Temperature coefficient (4.8.4.2)	20/- 55/20 °C and 20/125/20 °C	± 100 ppm/K	± 200 ppm/K			
Overload (4.13)	$U = 2.5 \times (P_{70} \times R)^{1/2}$ \$\le 2 \times U_{max.}; 0.5 \times	± (0.25 % <i>R</i> + 0.05 Ω)	± (0.5 % <i>R</i> + 0.05 Ω)			
Solderability (4.17.5) ⁽²⁾	Aging 4 h at 155 °C, dryheat solder bath method; 235 °C; 2 s visual examination	Good tinning (≥ 95 % covered) no visible damage				
Resistance to soldering heat (4.18.2)	ng heat (4.18.2) Solder bath method; (260 ± 5) °C; (10 ± 1) s		± (0.5 % <i>R</i> + 0.05 Ω)			
Rapid change of temperature (4.19)	30 min at LCT = - 55 °C; 30 min at UCT = 125 °C; 5 cycles	± (0.25 % <i>R</i> + 0.05 Ω)	± (0.5 % <i>R</i> + 0.05 Ω)			
Damp heat, steady state (4.24)	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (1 % <i>R</i> + 0.05 Ω)	± (2 % <i>R</i> + 0.1 Ω)			
Climatic sequence (4.23)	16 h at UCT = 125 °C; 1 cycle at 55 °C; 2 h at LCT = -55 °C; 1 h/1 kPa at 15 °C to 35 °C; 5 cycles at 55 °C $U = (P_{70} \times R)^{1/2}$ $U = U_{max.}$; whichever is less severe	± (1 % <i>R</i> + 0.05 Ω)	± (2 % R + 0.1 Ω)			
Endurance at 70 °C (4.25.1)	$U = (P_{70} \ge R)^{1/2}$ $U = U_{max}$; whichever is less severe 1.5 h ON; 0.5 h OFF; 70 °C; 1000 h	± (1 % <i>R</i> + 0.05 Ω)	± (2 % R + 0.1 Ω)			
Extended endurance (4.25.1.8)	Duration extended to 8000 h	± (2 % <i>R</i> + 0.1 Ω)	± (4 % <i>R</i> + 0.1 Ω)			
Endurance at upper category temperature (4.25.3)	UCT = 125 °C; 1000 h	± (1 % <i>R</i> + 0.05 Ω)	± (2 % <i>R</i> + 0.1 Ω)			

Notes

⁽¹⁾ Figures are given for a single element

(2) Solderability is specified for 2 years after production or requalification. Permitted storage time is 20 years

APPLICABLE SPECIFICATIONS

• EN 60115-1	Generic Specification
• EN 140400	Sectional Specification
• EN 140401-802	Detail Specification
• IEC 60068-2-X	Variety of environmental test procedures
• EIA 481	Packaging of SMD components



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